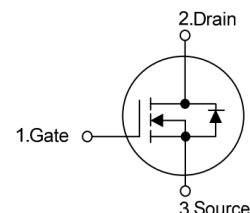
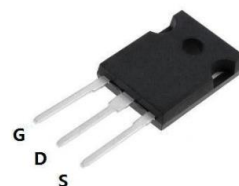


N-CHANNEL SiC POWER MOSFET

Features

- $R_{DS(on)}=40m\Omega$ (Typ.) @ $V_{GS}=20V, I_D=40A$
- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitance
- Fast intrinsic diode with low reverse recovery



Applications

- Solar inverters
- DC/DC converters
- Motor drives
- Switch Mode Power Supplies

Key Performance and Package Parameters

Order codes	V_{DS}	I_D	$R_{DS(ON)}$, Typ	T_{vjmax}	Marking	Package
XC040M120A1S3-A	1200V	55A	40m Ω	150 $^{\circ}C$	C40M120A1A	TO247-3

Absolute Maximum Ratings ($T_c=25^{\circ}C$ unless otherwise specified.)

Symbol	Parameter	Value	Units
V_{DSS}	Drain-Source Voltage	1200	V
V_{GSmax}	Absolute maximum Gate-Source Voltage	-10/+25	V
I_D	Continuous Drain Current ($T_C=25^{\circ}C$)	55	A
	Continuous Drain Current ($T_C=100^{\circ}C$)	36	A
$I_{DM(pulse)}$	Pulsed Drain Current, Pulse width t_p limited by T_{jmax}	160	A
P_D	Maximum Power Dissipation ($T_C=25^{\circ}C$)	278	W
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$

Thermal Data

Symbol	Parameter	Conditions	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Steady State)	TO247	0.45	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	TO247	40	$^{\circ}C/W$

Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise specified.)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=100\mu A$	1200	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=1200V, V_{GS}=0V$	---	1	100	μA
I_{GSS}	Gate Leakage Current, Forward	$V_{GS}=20V, V_{DS}=0V$	---	---	250	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=10mA$	2.0	3.2	4.0	V
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS}=20V, I_{DS}=40A$	---	40	52	$m\Omega$
Q_g	Total Gate Charge	$V_{DS}=800V$	---	120	---	nC
Q_{gs}	Gate-Source Charge	$V_{GS}=-5V/20V$	---	34	---	nC
Q_{gd}	Gate-Drain Charge	$I_{DS}=40A$	---	42	---	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=800V$	---	13	---	ns
t_r	Rise Time	$V_{GS}=-5V/20V$	---	61	--	ns
$t_{d(off)}$	Turn-off Delay Time	$I_{DS}=40A, R_G=2.5\Omega$	---	25	---	ns
t_f	Fall Time		---	13	---	ns
C_{iss}	Input Capacitance	$V_{DS}=1000V$	---	2440	---	pF
C_{oss}	Output Capacitance	$V_{GS}=0V$	---	171	---	pF
C_{rss}	Reverse Transfer Capacitance	$f=1MHz$	---	11	---	pF
E_{ON}	Turn-On Switching Energy (Body Diode)	$V_{DS}=800V,$ $V_{GS}=-5/20V,$	---	1.7	---	mJ
E_{OFF}	Turn Off Switching Energy (Body Diode)	$I_D=40A,$ $R_G=2.5\Omega$ $L=99\mu H$	---	0.4	---	mJ
E_{ON}	Turn-On Switching Energy (External Diode)	$V_{DS}=800V,$ $V_{GS}=-5/20V,$	---	1.3	---	mJ
E_{OFF}	Turn Off Switching Energy (External Diode)	$I_D=40A,$ $R_G=2.5\Omega$ $L=99\mu H$	---	0.4	---	mJ

Reverse Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{SD}	Diode Forward Voltage	$I_{SD}=20A, V_{GS}=-5V$	---	4	---	V
I_S	Continuous Diode Forward Current	$T_c=25^\circ\text{C}$	---	---	60	A
t_{rr}	Diode Reverse Recovery	$V_R=800V,$	---	54	---	ns

	Time	I _{SD} =40A, di _f /dt=1000A/s				
Q _{rr}	Diode Reverse Recovery Charge		---	283	---	nC
I _{rrm}	Peak Reverse Recovery Current		---	15	---	A

Typical Characteristics

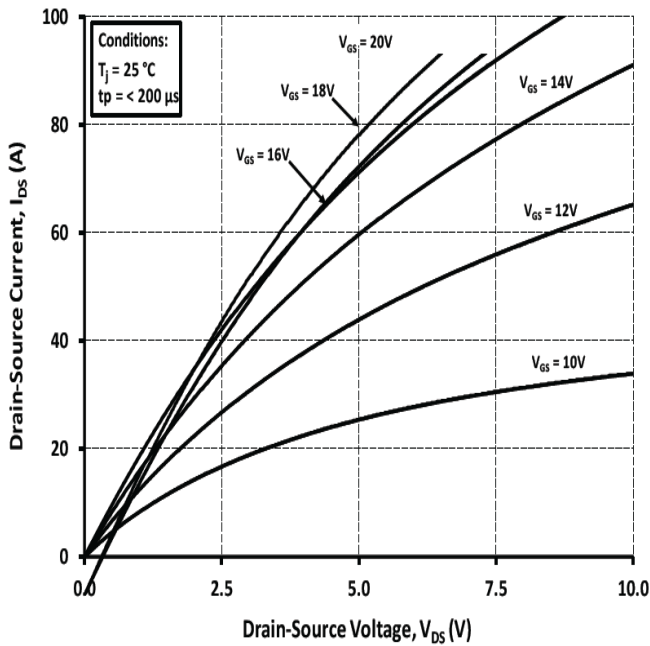


Fig.1 Output Characteristics

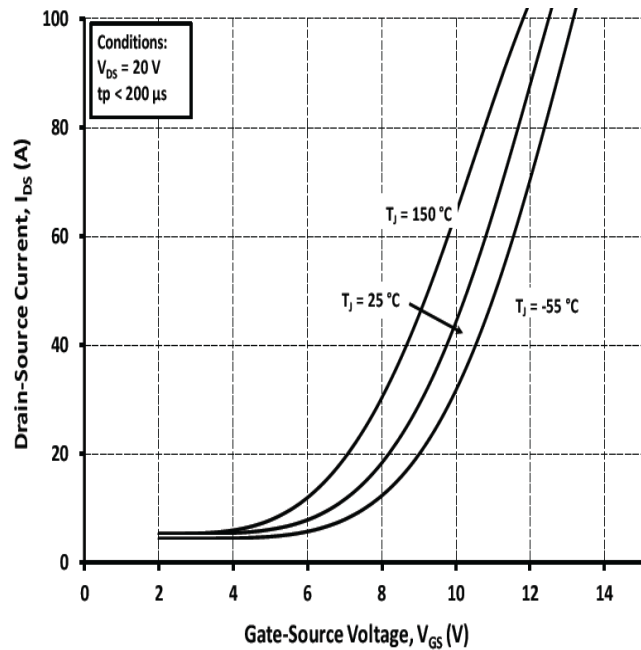


Fig.2 Output Characteristics

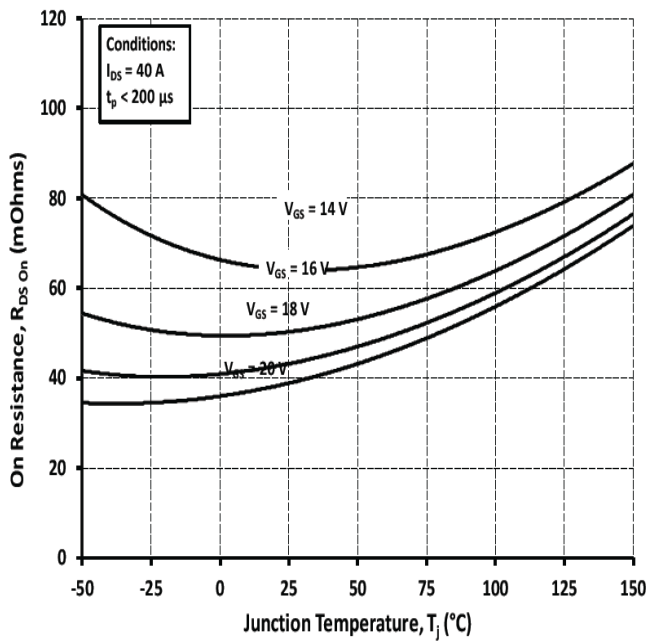


Fig.3 Drain-Source On Resistance

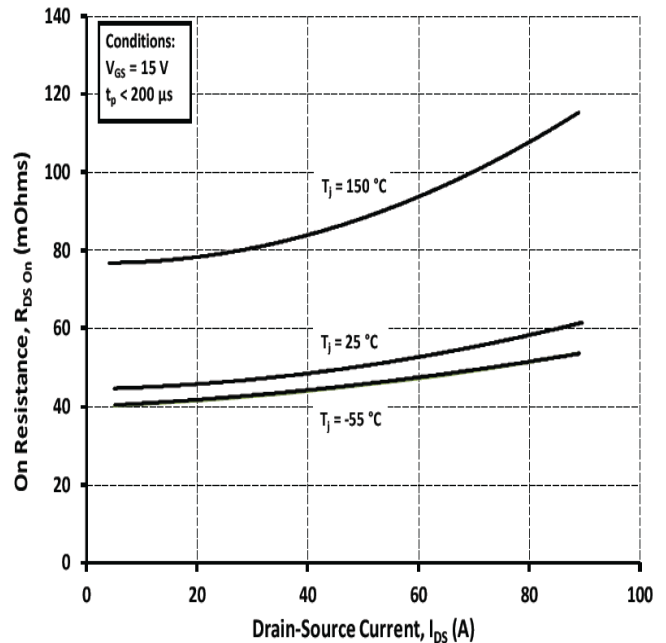


Fig.4 Drain-Source On Resistance

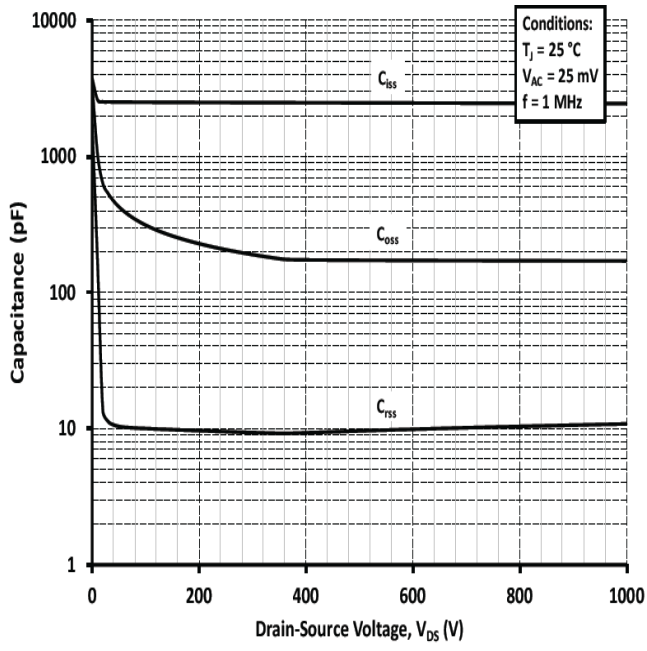


Fig.5 Capacitance

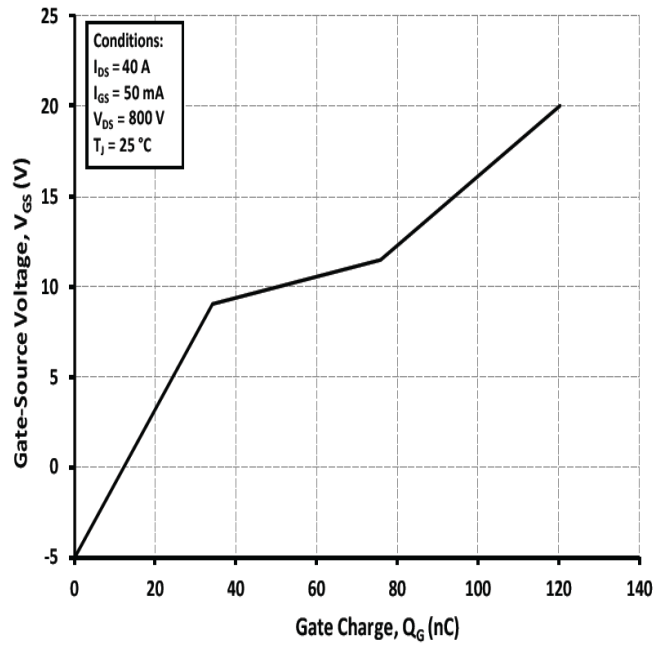
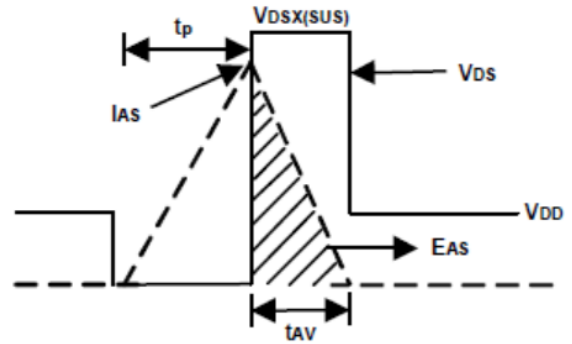
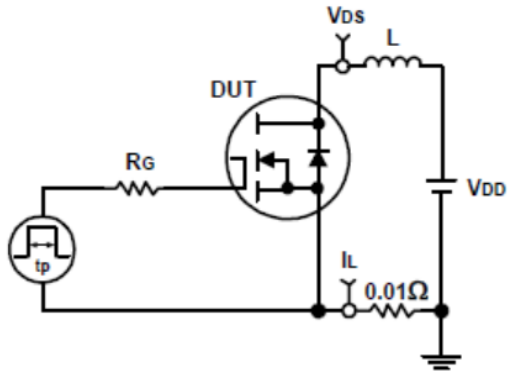


Fig.6 Gate Charge Characteristics

Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms

